

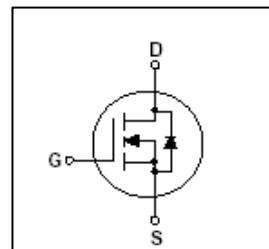
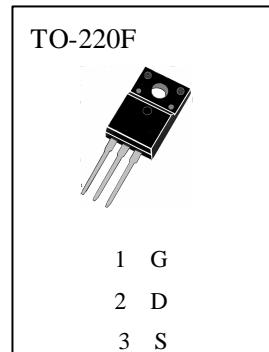


Shantou Huashan Electronic Devices Co.,Ltd.

N-Channel MOSFET

HFF2N60**APPLICATIONS**

High-Speed Switching.

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ C$) T_{stg} —— Storage Temperature -55~150 T_j —— Operating Junction Temperature 150 P_D —— Allowable Power Dissipation ($T_c=25^\circ C$) 23W V_{DSS} —— Drain-Source Voltage 600V V_{GSS} —— Gate-Source Voltage $\pm 30V$ I_D —— Drain Current ($T_c=25^\circ C$) 2.0A**ELECTRICAL CHARACTERISTICS ($T_a=25^\circ C$)**

Symbol	Characteristics	Min	Typ	Max	Unit	Test Conditions
BV_{DSS}	Drain-Source Breakdown Voltage	600			V	$I_D=250 \mu A, V_{GS}=0V$
I_{DSS}	Zero Gate Voltage Drain Current			10	μA	$V_{DS}=600V, V_{GS}=0$
I_{GSS}	Gate –Source Leakage Current			± 100	nA	$V_{GS}=\pm 30V, V_{DS}=0V$
$V_{GS(th)}$	Gate Threshold Voltage	2.0		4.0	V	$V_{DS}=V_{GS}, I_D=250 \mu A$
$R_{DS(on)}$	Static Drain-Source On-Resistance		3.8	5.0		$V_{GS}=10V, I_D=1.0A$
g_{fs}	Forward Transconductance		2.05		S	$V_{DS}=40V, I_D=1.0A$ *
C_{iss}	Input Capacitance	180	235		pF	$V_{DS}=25V, V_{GS}=0, f=1MHz$
C_{oss}	Output Capacitance	20	25		pF	
C_{rss}	Reverse Transfer Capacitance	4.3	3		pF	
$t_{d(on)}$	Turn - On Delay Time		9	28	nS	$V_{DD}=300V, I_D=2A$ (峰值) $R_G=25$
t_r	Rise Time		25	60	nS	
$t_{d(off)}$	Turn - Off Delay Time		24	58	nS	
t_f	Fall Time		28	66	nS	$V_{DS}=480V$ $V_{GS}=10V$ $I_D=2A$
Q_g	Total Gate Charge	8.5	12		nC	
Q_{gs}	Gate–Source Charge		1.3		nC	
Q_{gd}	Gate–Drain Charge		4.1		nC	$I_S=2.0A, V_{GS}=0$
I_s	Continuous Source Current			2.0	A	
V_{SD}	Diode Forward Voltage			1.4	V	
$R_{th(j-c)}$	Thermal Resistance , Junction-to-Case			5.5	/W	

*Pulse Test : Pulse Width 300 μs , Duty Cycle 2%



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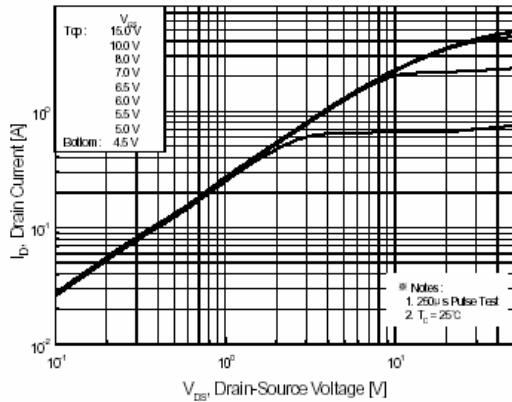


Figure 1. On-Region Characteristics

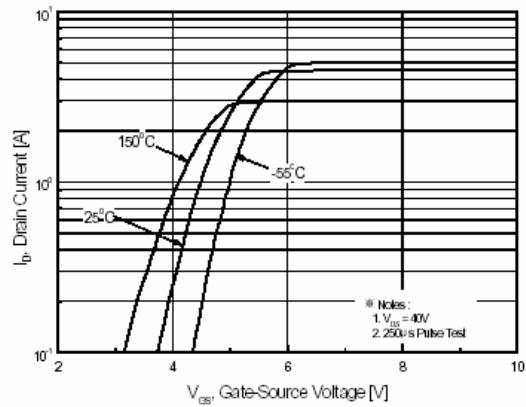


Figure 2. Transfer Characteristics

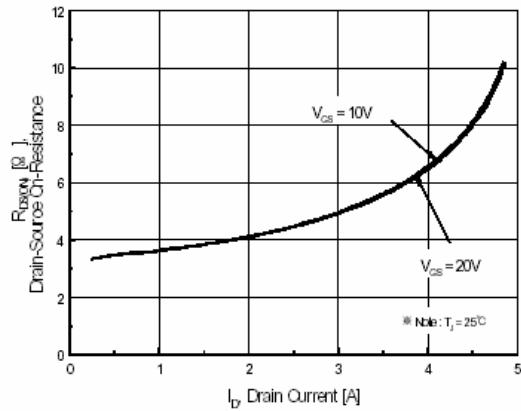


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

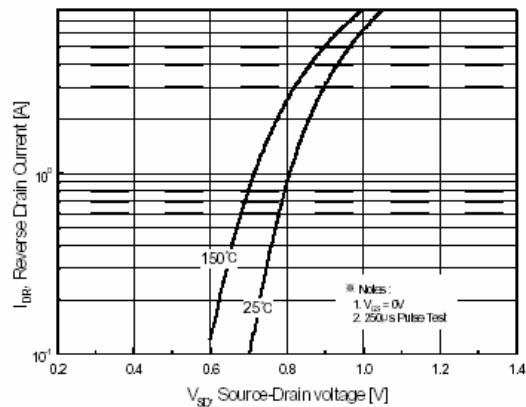


Figure 4. Body Diode Forward Voltage Variation with Source Current and Temperature

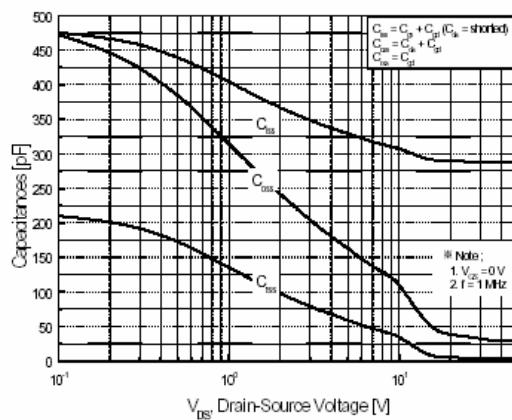


Figure 5. Capacitance Characteristics

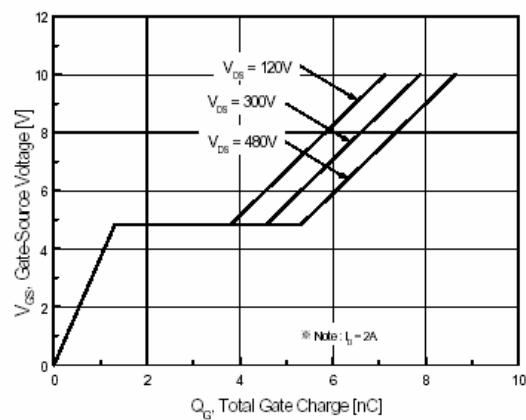


Figure 6. Gate Charge Characteristics



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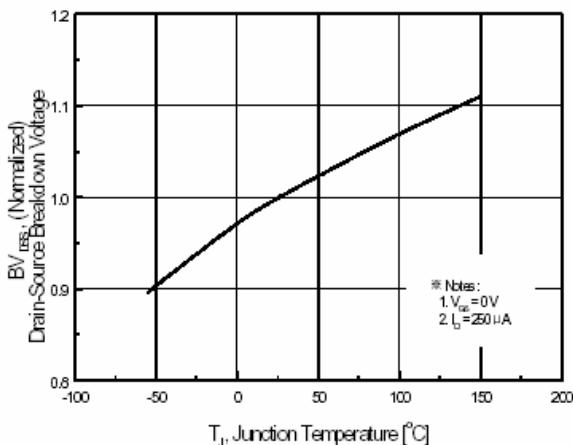


Figure 7. Breakdown Voltage Variation vs Temperature

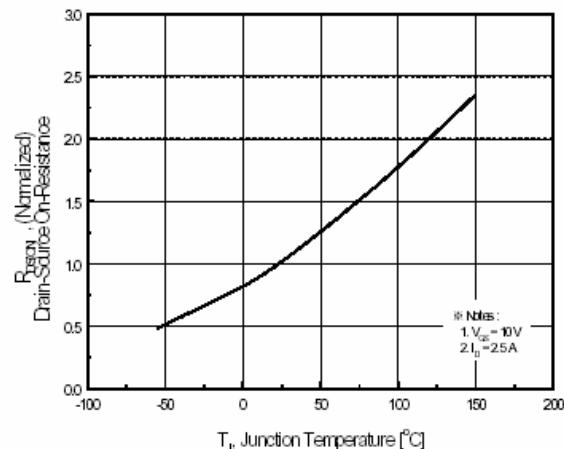


Figure 8. On-Resistance Variation vs Temperature

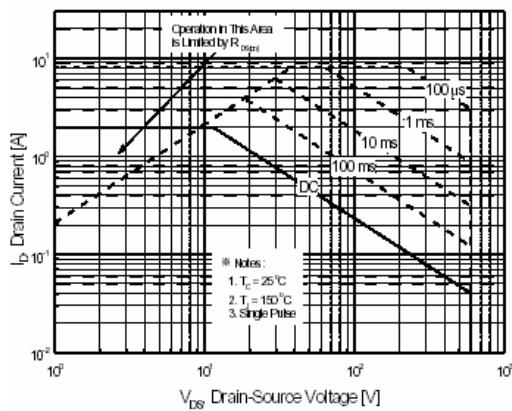


Figure 9-2. Maximum Safe Operating Area for HFF2N60

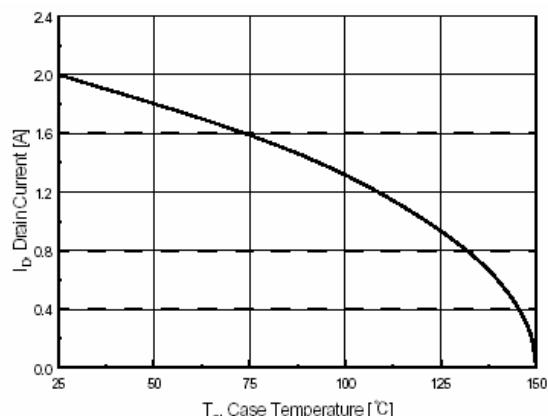


Figure 10. Maximum Drain Current vs Case Temperature

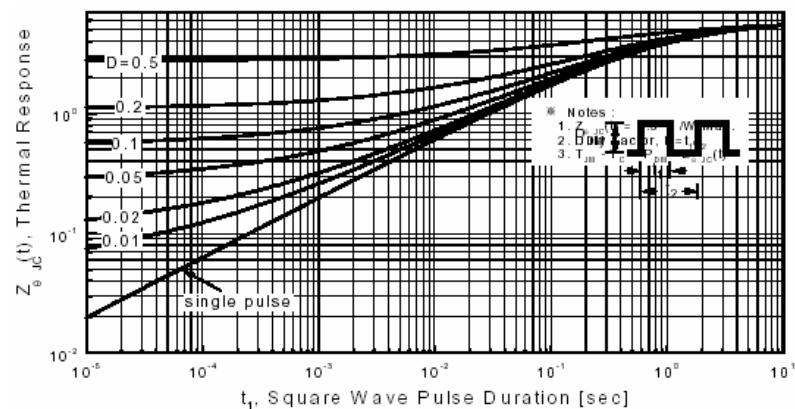


Figure 11-2. Transient Thermal Response Curve for HFF2N60

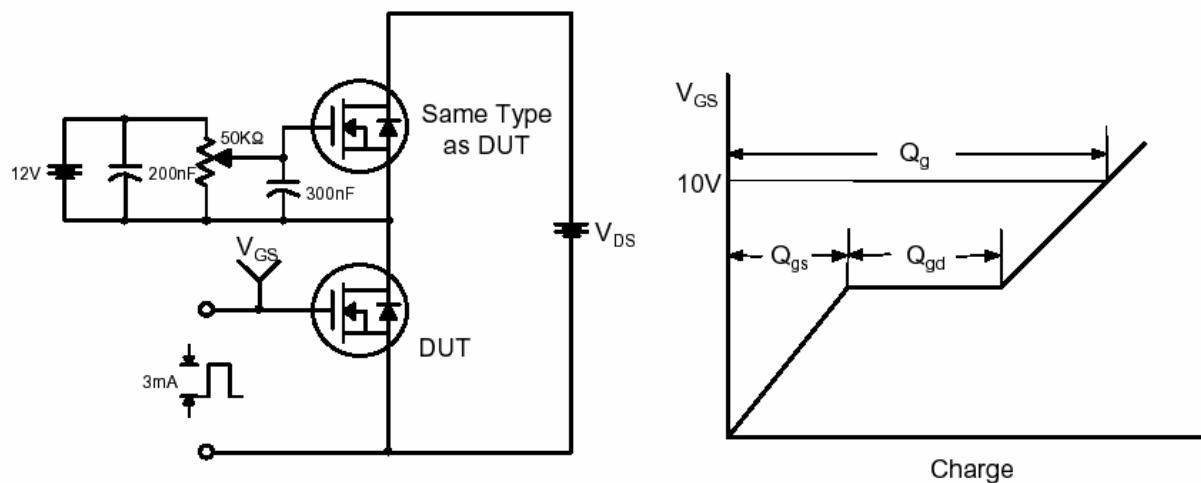


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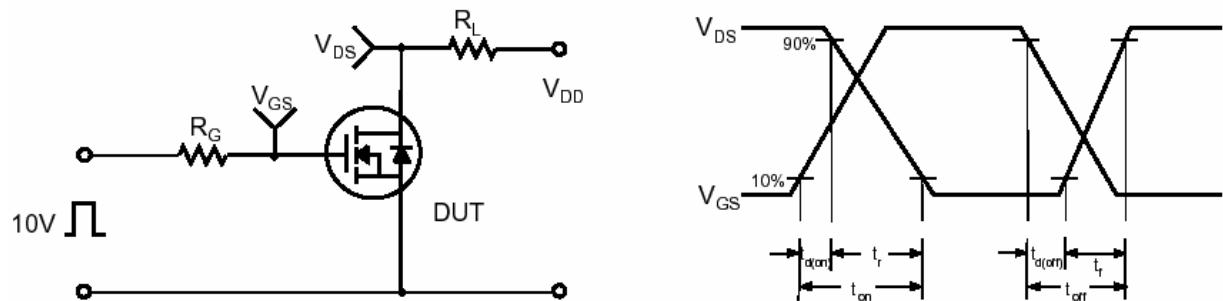
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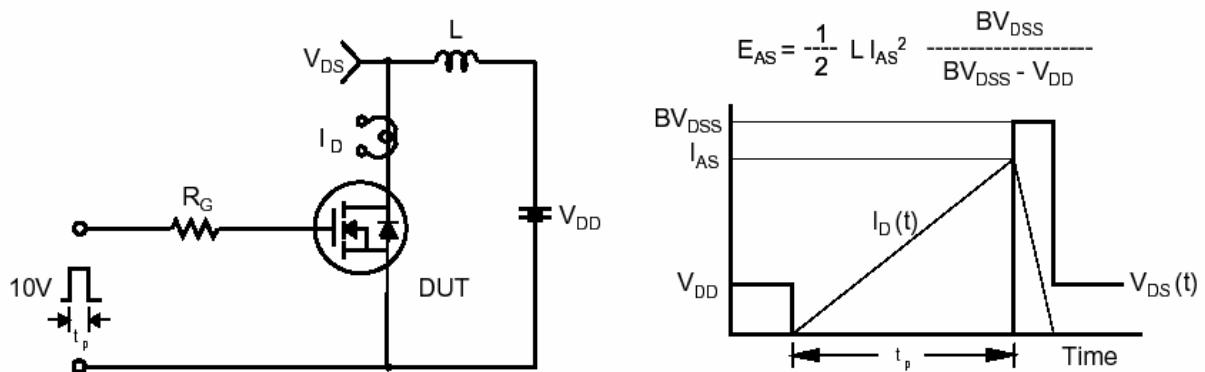
Gate Charge Test Circuit & Waveform



Resistive Switching Test Circuit & Waveforms



Unclamped Inductive Switching Test Circuit & Waveforms





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N-Channel MOSFET

HFF2N60

Peak Diode Recovery dv/dt Test Circuit & Waveforms

